	Application No.	Applicant(s)
Notice of Allowability	10/687,713 Examiner	HUANG ET AL. Art Unit
•		·
<u> </u>	Lan Vinh	1765
The MAILING DATE of this communication appears on the cover sheet with the correspondence address All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS. This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.		
1. This communication is responsive to <i>The Amendment and response filed on 2/26/2007</i> .		
2. The allowed claim(s) is/are <u>1 and 20-30</u> .		
 3. Acknowledgment is made of a claim for foreign priority uner a) All b) Some* c) None of the: 1. Certified copies of the priority documents have 	been received.	
2. Certified copies of the priority documents have been received in Application No		
3. Copies of the certified copies of the priority documents have been received in this national stage application from the		
International Bureau (PCT Rule 17.2(a)).		
* Certified copies not received:		
Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application. THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.		
4. A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.		
5. CORRECTED DRAWINGS (as "replacement sheets") must be submitted.		
(a) ☐ including changes required by the Notice of Draftsperson's Patent Drawing Review (PTO-948) attached		
1) 🗌 hereto or 2) 🔲 to Paper No./Mail Date		
(b) ☐ including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date		
Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d).		
6. DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL.		
Attachment(s)	_	·
1. Notice of References Cited (PTO-892)	5. Notice of Informal Pa	
2. Notice of Draftperson's Patent Drawing Review (PTO-948)	6. ⊠ Interview Summary (Paper No./Mail Date	
 Information Disclosure Statements (PTO/SB/08), Paper No./Mail Date 	7. 🛛 Examiner's Amendm	nent/Comment
4. Examiner's Comment Regarding Requirement for Deposit	8. Examiner's Stateme	nt of Reasons for Allowance
of Biological Material	9.	Lan Vinh AU 1765
		7.5 7766

EXAMINER'S AMENDMENT

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Richard Paikoff on 5/9/2007.

The application has been amended as follows:

Claims 31-38 have been cancelled

Allowable Subject Matter

2. Claims 1, 20-30 allowed.

The following is an examiner's statement of reasons for allowance:

Regarding claim 1, the applicants have presented persuasive arguments, see pages 5-6 of the response filed on 2/26/2007, that there would be no reasonable expectation to combine the teaching of Kakamu and Leu, whose teaching related to a method to improve nucleation of a CVD deposited layer, to meet the amended limitation of "treating the top surface of the low-k interlayer dielectric layer to transform a thin surface layer of the low-k interlayer dielectric layer into a copper diffusion barrier, wherein the step of treating the top surface of the low-k interlayer dielectric layer employs consists essentially of ion implantation using carbon dioxide, and wherein the copper diffusion barrier is a layer of silicon carbide less than 50 angstroms thick" since CVD is a

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chemical process used to produce thin films, while ion implantation is a materials engineering process by which the ions of a material are implanted into another solid and the claims have been further clarified so as to exclude the process gas tetra methyl silane, disclosed in paragraph [0056] of Kakamu. Thus, the rejection(s) of claims 1, 17. 20-21-25 26, 28, 29 under 35 U.S.C 103(a) based on Leu and Kakamu has been withdrawn

Conclusion

3. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Lan Vinh whose telephone number is 571 272 1471. The examiner can normally be reached on M-F 8:30-5:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on 571 272 1465. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov.

May 9, 2007